

# 74LVC332

## Triple 3-input OR gate

Rev. 1 — 20 March 2013

Product data sheet

## 1. General description

The 74LVC332 is a triple 3-input OR gate.

Inputs can be driven from either 3.3 V or 5 V devices. This feature allows the use of these devices as translators in mixed 3.3 V and 5 V environments. Schmitt-trigger action at all inputs makes the circuit tolerant of slower input rise and fall times.

## 2. Features and benefits

- Wide supply voltage range from 1.2 V to 3.6 V
- Inputs accept voltages up to 5.5 V
- CMOS low power consumption
- Direct interface with TTL levels
- Complies with JEDEC standard:
  - ◆ JESD8-7A (1.65 V to 1.95 V)
  - ◆ JESD8-5A (2.3 V to 2.7 V)
  - ◆ JESD8-C/JESD36 (2.7 V to 3.6 V)
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-B exceeds 200 V
  - ◆ CDM JESD22-C101E exceeds 1000 V
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$

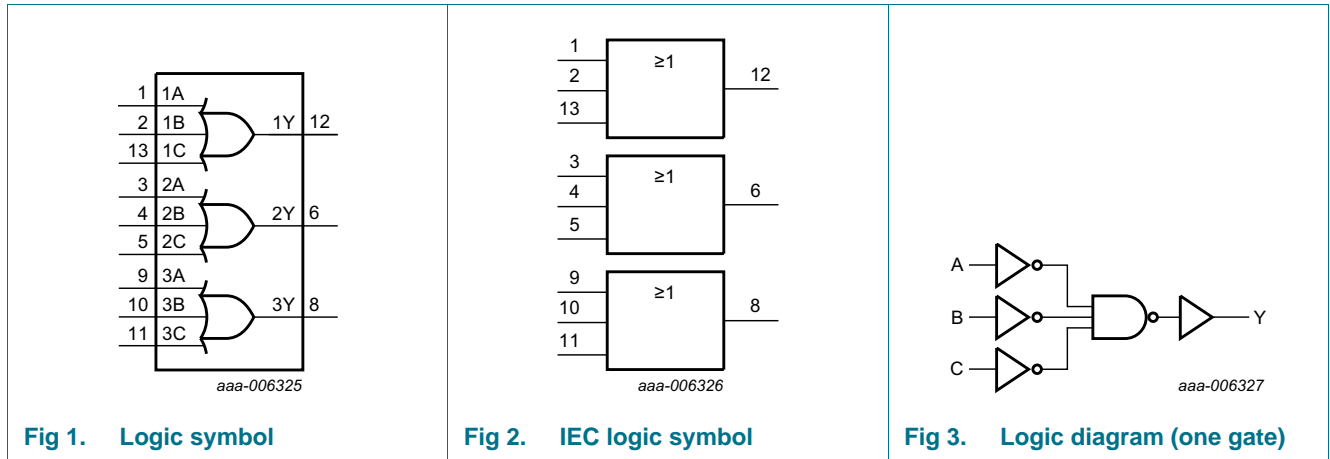
## 3. Ordering information

Table 1. Ordering information

| Type number | Package   |          |   | Version  |
|-------------|---|----------|---|----------|
|             | Temperature range   | Name     | Description   |          |
| 74LVC332D   | $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ | SO14     | plastic small outline package; 14 leads; body width 3.9 mm  | SOT108-1 |
| 74LVC332DB  | $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ | SSOP14   | plastic shrink small outline package; 14 leads; body width 5.3 mm   | SOT337-1 |
| 74LVC332PW  | $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ | TSSOP14  | plastic thin shrink small outline package; 14 leads; body width 4.4 mm  | SOT402-1 |
| 74LVC332BQ  | $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ | DHVQFN14 | plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body $2.5 \times 3 \times 0.85\text{ mm}$ | SOT762-1 |

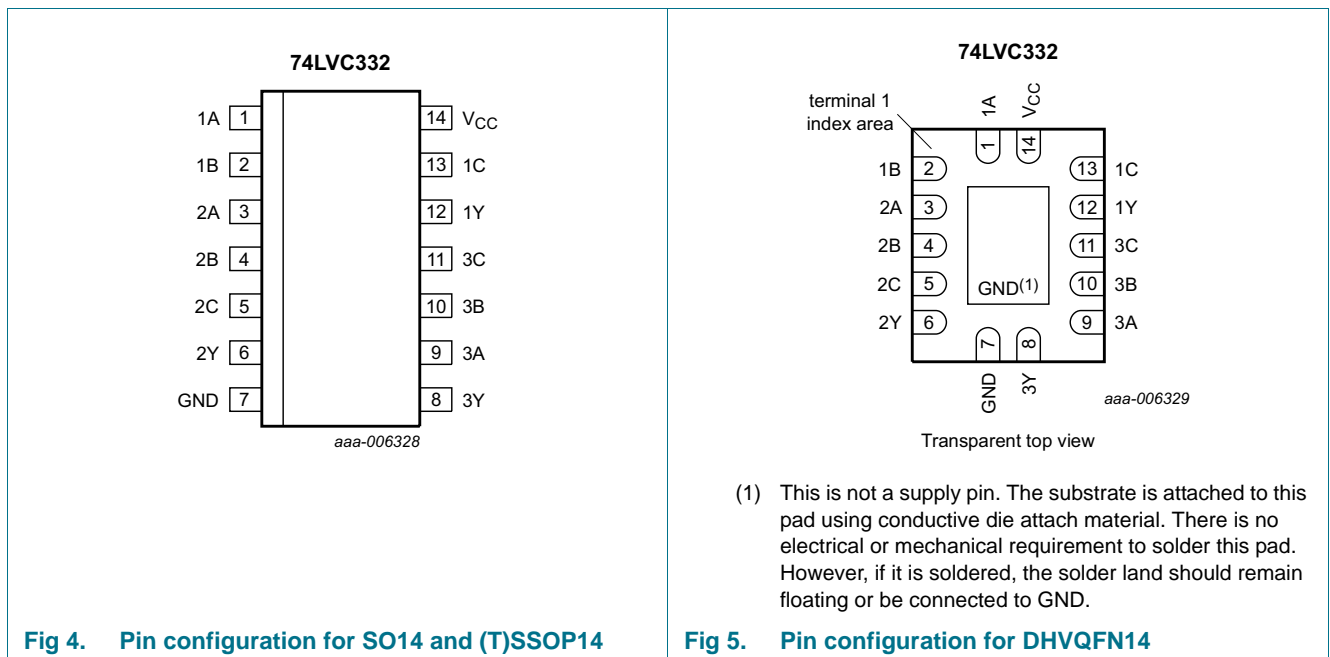


## 4. Functional diagram



## 5. Pinning information

### 5.1 Pinning



## 5.2 Pin description

Table 2. Pin description

| Symbol          | Pin       | Description    |
|-----------------|-----------|----------------|
| 1A, 2A, 3A      | 1, 3, 9   | data input     |
| 1B, 2B, 3B      | 2, 4, 10  | data input     |
| 1C, 2C, 3C      | 13, 5, 11 | data input     |
| 1Y, 2Y, 3Y      | 12, 6, 8  | data output    |
| GND             | 7         | ground (0 V)   |
| V <sub>CC</sub> | 14        | supply voltage |

## 6. Functional description

Table 3. Function selection<sup>[1]</sup>

| Input |    |    | Output |
|-------|----|----|--------|
| nA    | nB | nC | nY     |
| L     | L  | L  | L      |
| X     | X  | H  | H      |
| X     | H  | X  | H      |
| H     | X  | X  | H      |

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care

## 7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

| Symbol           | Parameter               | Conditions   | Min                 | Max                   | Unit |
|------------------|-------------------------|--|---------------------|-----------------------|------|
| V <sub>CC</sub>  | supply voltage          |  | -0.5                | +6.5                  | V    |
| I <sub>IK</sub>  | input clamping current  | V <sub>I</sub> < 0                                     | -50                 | -                     | mA   |
| V <sub>I</sub>   | input voltage           |  | <sup>[1]</sup> -0.5 | +5.5                  | V    |
| I <sub>OK</sub>  | output clamping current | V <sub>O</sub> > V <sub>CC</sub> or V <sub>O</sub> < 0 | -                   | ±50                   | mA   |
| V <sub>O</sub>   | output voltage          |  | <sup>[2]</sup> -0.5 | V <sub>CC</sub> + 0.5 | V    |
| I <sub>O</sub>   | output current          | V <sub>O</sub> = 0 V to V <sub>CC</sub>                | -                   | ±50                   | mA   |
| I <sub>CC</sub>  | supply current          |  | -                   | 100                   | mA   |
| I <sub>GND</sub> | ground current          |  | -100                | -                     | mA   |
| T <sub>stg</sub> | storage temperature     |  | -60                 | +150                  | °C   |
| P <sub>tot</sub> | total power dissipation | T <sub>amb</sub> = -40 °C to +85 °C                    | <sup>[3]</sup> -    | 500                   | mW   |

[1] The minimum input voltage ratings may be exceeded if the input current ratings are observed.

[2] The output voltage ratings may be exceeded if the output current ratings are observed.

[3] For SO14 packages: above 70 °C the value of P<sub>tot</sub> derates linearly with 8 mW/K.  
 For (T)SSOP14 packages: above 60 °C the value of P<sub>tot</sub> derates linearly with 5.5 mW/K.  
 For DHVQFN14 packages: above 60 °C the value of P<sub>tot</sub> derates linearly with 4.5 mW/K.

## 8. Recommended operating conditions

**Table 5. Recommended operating conditions**

| Symbol           | Parameter                           | Conditions                        | Min  | Typ | Max             | Unit |
|------------------|-------------------------------------|-----------------------------------|------|-----|-----------------|------|
| V <sub>CC</sub>  | supply voltage                      |                                   | 1.65 | -   | 3.6             | V    |
|                  |                                     | functional                        | 1.2  | -   | -               | V    |
| V <sub>I</sub>   | input voltage                       |                                   | 0    | -   | 5.5             | V    |
| V <sub>O</sub>   | output voltage                      |                                   | 0    | -   | V <sub>CC</sub> | V    |
| T <sub>amb</sub> | ambient temperature                 | in free air                       | -40  | -   | +85             | °C   |
| Δt/ΔV            | input transition rise and fall rate | V <sub>CC</sub> = 1.65 V to 2.7 V | 0    | -   | 20              | ns/V |
|                  |                                     | V <sub>CC</sub> = 2.7 V to 3.6 V  | 0    | -   | 10              | ns/V |

## 9. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

| Symbol          | Parameter                 | Conditions  | -40 °C to +85 °C       |                    |                        | -40 °C to +125 °C      |                        | Unit |
|-----------------|---------------------------|---|------------------------|--------------------|------------------------|------------------------|------------------------|------|
|                 |                           |   | Min                    | Typ <sup>[1]</sup> | Max                    | Min                    | Max                    |      |
| V <sub>IH</sub> | HIGH-level input voltage  | V <sub>CC</sub> = 1.2 V                                     | 1.08                   | -                  | -                      | 1.08                   | -                      | V    |
|                 |                           | V <sub>CC</sub> = 1.65 V to 1.95 V                          | 0.65 × V <sub>CC</sub> | -                  | -                      | 0.65 × V <sub>CC</sub> | -                      | V    |
|                 |                           | V <sub>CC</sub> = 2.3 V to 2.7 V                            | 1.7                    | -                  | -                      | 1.7                    | -                      | V    |
|                 |                           | V <sub>CC</sub> = 2.7 V to 3.6 V                            | 2.0                    | -                  | -                      | 2.0                    | -                      | V    |
| V <sub>IL</sub> | LOW-level input voltage   | V <sub>CC</sub> = 1.2 V                                     | -                      | -                  | 0.12                   | -                      | 0.12                   | V    |
|                 |                           | V <sub>CC</sub> = 1.65 V to 1.95 V                          | -                      | -                  | 0.35 × V <sub>CC</sub> | -                      | 0.35 × V <sub>CC</sub> | V    |
|                 |                           | V <sub>CC</sub> = 2.3 V to 2.7 V                            | -                      | -                  | 0.7                    | -                      | 0.7                    | V    |
|                 |                           | V <sub>CC</sub> = 2.7 V to 3.6 V                            | -                      | -                  | 0.8                    | -                      | 0.8                    | V    |
| V <sub>OH</sub> | HIGH-level output voltage | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>         |                        |                    |                        |                        |                        |      |
|                 |                           | I <sub>O</sub> = -100 μA; V <sub>CC</sub> = 1.65 V to 3.6 V | V <sub>CC</sub> - 0.2  | -                  | -                      | V <sub>CC</sub> - 0.3  | -                      | V    |
|                 |                           | I <sub>O</sub> = -4 mA; V <sub>CC</sub> = 1.65 V            | 1.2                    | -                  | -                      | 1.05                   | -                      | V    |
|                 |                           | I <sub>O</sub> = -8 mA; V <sub>CC</sub> = 2.3 V             | 1.8                    | -                  | -                      | 1.65                   | -                      | V    |
|                 |                           | I <sub>O</sub> = -12 mA; V <sub>CC</sub> = 2.7 V            | 2.2                    | -                  | -                      | 2.05                   | -                      | V    |
|                 |                           | I <sub>O</sub> = -18 mA; V <sub>CC</sub> = 3.0 V            | 2.4                    | -                  | -                      | 2.25                   | -                      | V    |
| V <sub>OL</sub> | LOW-level output voltage  | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>         |                        |                    |                        |                        |                        |      |
|                 |                           | I <sub>O</sub> = 100 μA; V <sub>CC</sub> = 1.65 V to 3.6 V  | -                      | -                  | 0.2                    | -                      | 0.3                    | V    |
|                 |                           | I <sub>O</sub> = 4 mA; V <sub>CC</sub> = 1.65 V             | -                      | -                  | 0.45                   | -                      | 0.65                   | V    |
|                 |                           | I <sub>O</sub> = 8 mA; V <sub>CC</sub> = 2.3 V              | -                      | -                  | 0.6                    | -                      | 0.8                    | V    |
|                 |                           | I <sub>O</sub> = 12 mA; V <sub>CC</sub> = 2.7 V             | -                      | -                  | 0.4                    | -                      | 0.6                    | V    |
|                 |                           | I <sub>O</sub> = 24 mA; V <sub>CC</sub> = 3.0 V             | -                      | -                  | 0.55                   | -                      | 0.8                    | V    |
| I <sub>I</sub>  | input leakage current     | V <sub>CC</sub> = 3.6 V; V <sub>I</sub> = 5.5 V or GND      | -                      | ±0.1               | ±5                     | -                      | ±20                    | μA   |

**Table 6. Static characteristics ...continued**

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

| Symbol           | Parameter                 | Conditions  | -40 °C to +85 °C |                    |     | -40 °C to +125 °C |      | Unit |
|------------------|---------------------------|---|------------------|--------------------|-----|-------------------|------|------|
|                  |                           |   | Min              | Typ <sup>[1]</sup> | Max | Min               | Max  |      |
| I <sub>CC</sub>  | supply current            | V <sub>CC</sub> = 3.6 V; V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A                          | -                | 0.1                | 10  | -                 | 40   | μA   |
| ΔI <sub>CC</sub> | additional supply current | per input pin; V <sub>CC</sub> = 2.7 V to 3.6 V; V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0 A | -                | 5                  | 500 | -                 | 5000 | μA   |
| C <sub>I</sub>   | input capacitance         | V <sub>CC</sub> = 0 V to 3.6 V; V <sub>I</sub> = GND to V <sub>CC</sub>   | -                | 5.0                | -   | -                 | -    | pF   |

[1] All typical values are measured at V<sub>CC</sub> = 3.3 V (unless stated otherwise) and T<sub>amb</sub> = 25 °C.

## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**

Voltages are referenced to GND (ground = 0 V). For test circuit see [Figure 7](#).

| Symbol          | Parameter                     | Conditions   | -40 °C to +85 °C |                    |      | -40 °C to +125 °C |      | Unit |
|-----------------|-------------------------------|--|------------------|--------------------|------|-------------------|------|------|
|                 |                               |  | Min              | Typ <sup>[1]</sup> | Max  | Min               | Max  |      |
| t <sub>pd</sub> | propagation delay             | nA, nB, nC to nY; see <a href="#">Figure 6</a> <sup>[2]</sup>    |                  |                    |      |                   |      |      |
|                 |                               | V <sub>CC</sub> = 1.65 V to 1.95 V                               | 0.5              | 4.6                | 11.6 | 0.5               | 13.4 | ns   |
|                 |                               | V <sub>CC</sub> = 2.3 V to 2.7 V                                 | 1.0              | 2.7                | 6.6  | 1.0               | 7.6  | ns   |
|                 |                               | V <sub>CC</sub> = 2.7 V  | 1.1              | 2.8                | 7.0  | 1.1               | 8.1  | ns   |
|                 |                               | V <sub>CC</sub> = 3.0 V to 3.6 V                                 | 0.8              | 2.4                | 5.9  | 0.8               | 6.8  | ns   |
| C <sub>PD</sub> | power dissipation capacitance | per gate; V <sub>I</sub> = GND to V <sub>CC</sub> <sup>[3]</sup> |                  |                    |      |                   |      |      |
|                 |                               | V <sub>CC</sub> = 1.65 V to 1.95 V                               | -                | 8.1                | -    | -                 | -    | pF   |
|                 |                               | V <sub>CC</sub> = 2.3 V to 2.7 V                                 | -                | 8.2                | -    | -                 | -    | pF   |
|                 |                               | V <sub>CC</sub> = 3.0 V to 3.6 V                                 | -                | 9.2                | -    | -                 | -    | pF   |

[1] Typical values are measured at T<sub>amb</sub> = 25 °C and V<sub>CC</sub> = 1.2 V, 1.8 V, 2.5 V, 2.7 V, and 3.3 V respectively.

[2] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>.

[3] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f<sub>i</sub> = input frequency in MHz; f<sub>o</sub> = output frequency in MHz

C<sub>L</sub> = output load capacitance in pF

V<sub>CC</sub> = supply voltage in Volts

N = number of inputs switching

Σ(C<sub>L</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) = sum of the outputs

11. AC waveforms

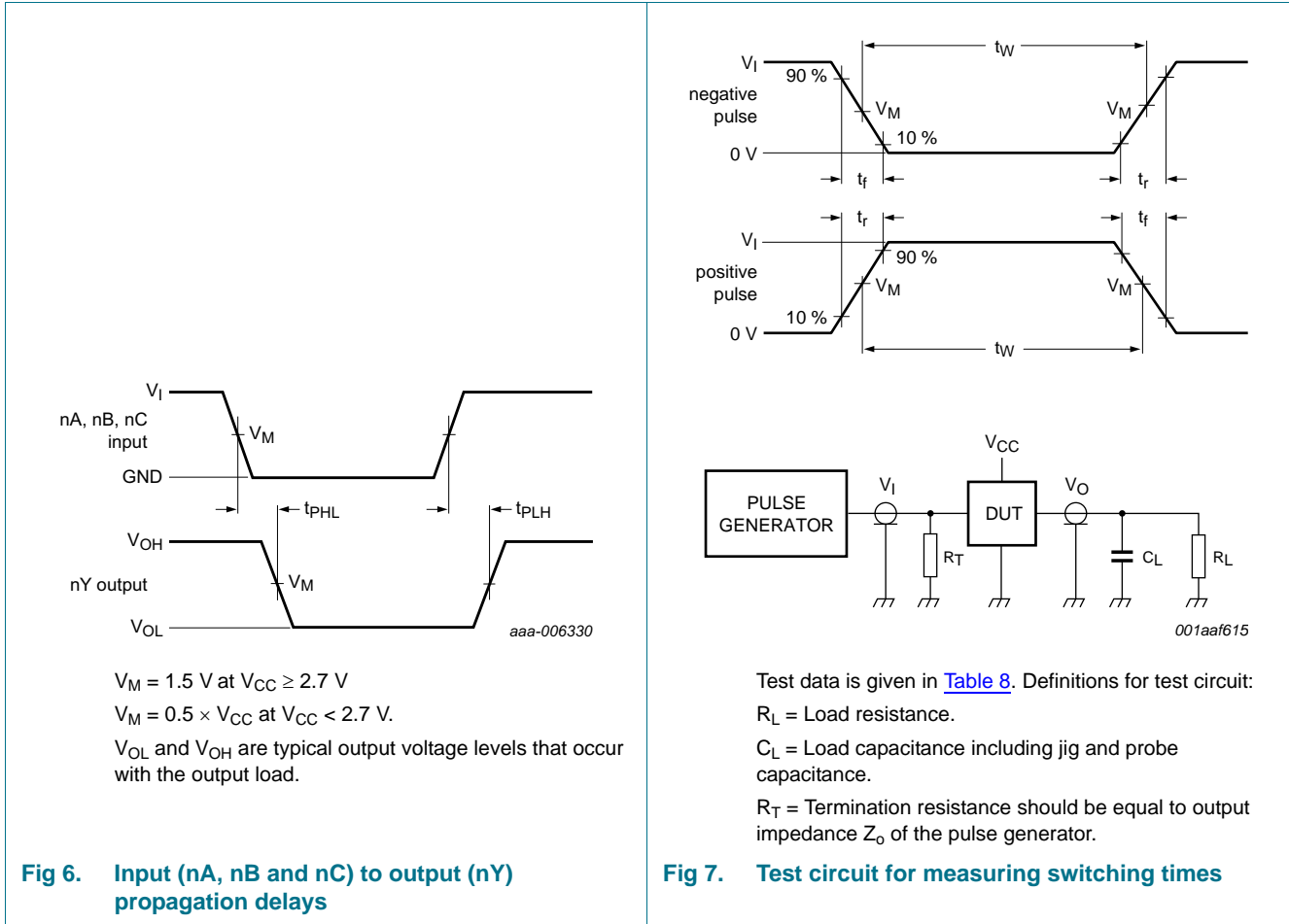


Table 8. Test data

| Supply voltage   | Input    |                      | Load  |              |
|------------------|----------|----------------------|-------|--------------|
|                  | $V_I$    | $t_r, t_f$           | $C_L$ | $R_L$        |
| 1.2 V            | $V_{CC}$ | $\leq 2\text{ ns}$   | 30 pF | 1 k $\Omega$ |
| 1.65 V to 1.95 V | $V_{CC}$ | $\leq 2\text{ ns}$   | 30 pF | 1 k $\Omega$ |
| 2.3 V to 2.7 V   | $V_{CC}$ | $\leq 2\text{ ns}$   | 30 pF | 500 $\Omega$ |
| 2.7 V            | 2.7 V    | $\leq 2.5\text{ ns}$ | 50 pF | 500 $\Omega$ |
| 3.0 V to 3.6 V   | 2.7 V    | $\leq 2.5\text{ ns}$ | 50 pF | 500 $\Omega$ |

## 12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

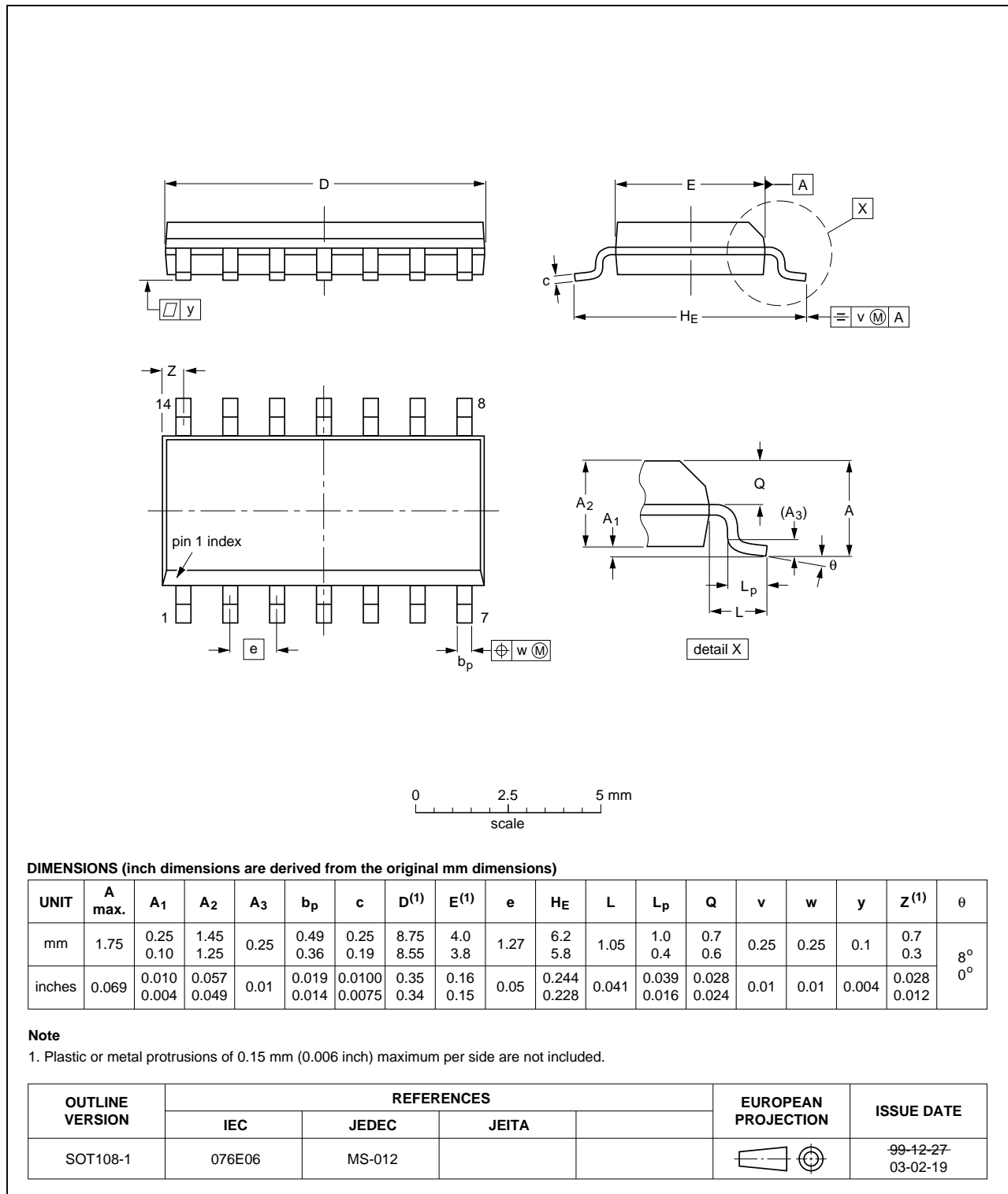


Fig 8. Package outline SOT108-1 (SO14)

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1

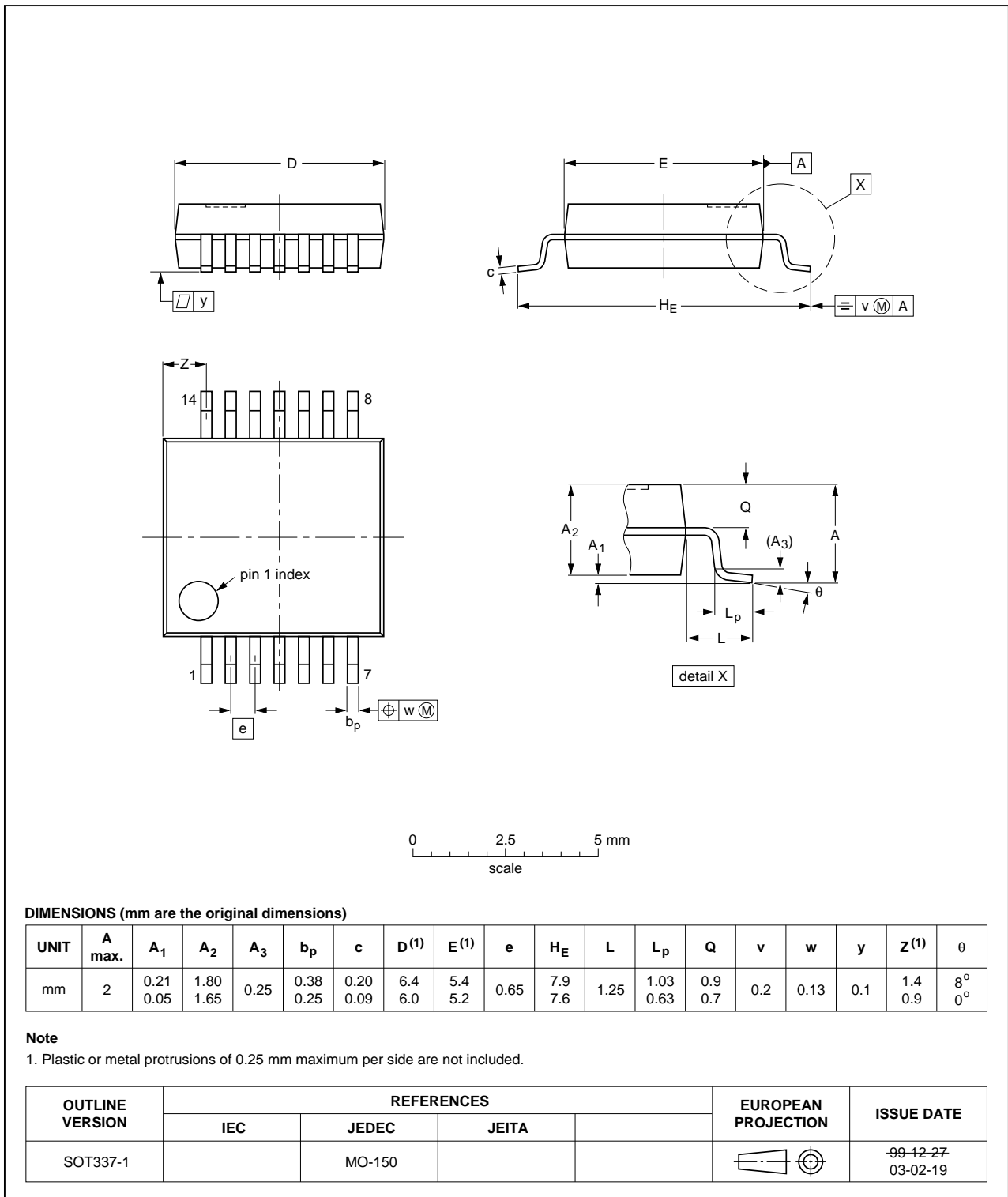


Fig 9. Package outline SOT337-1 (SSOP14)



TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

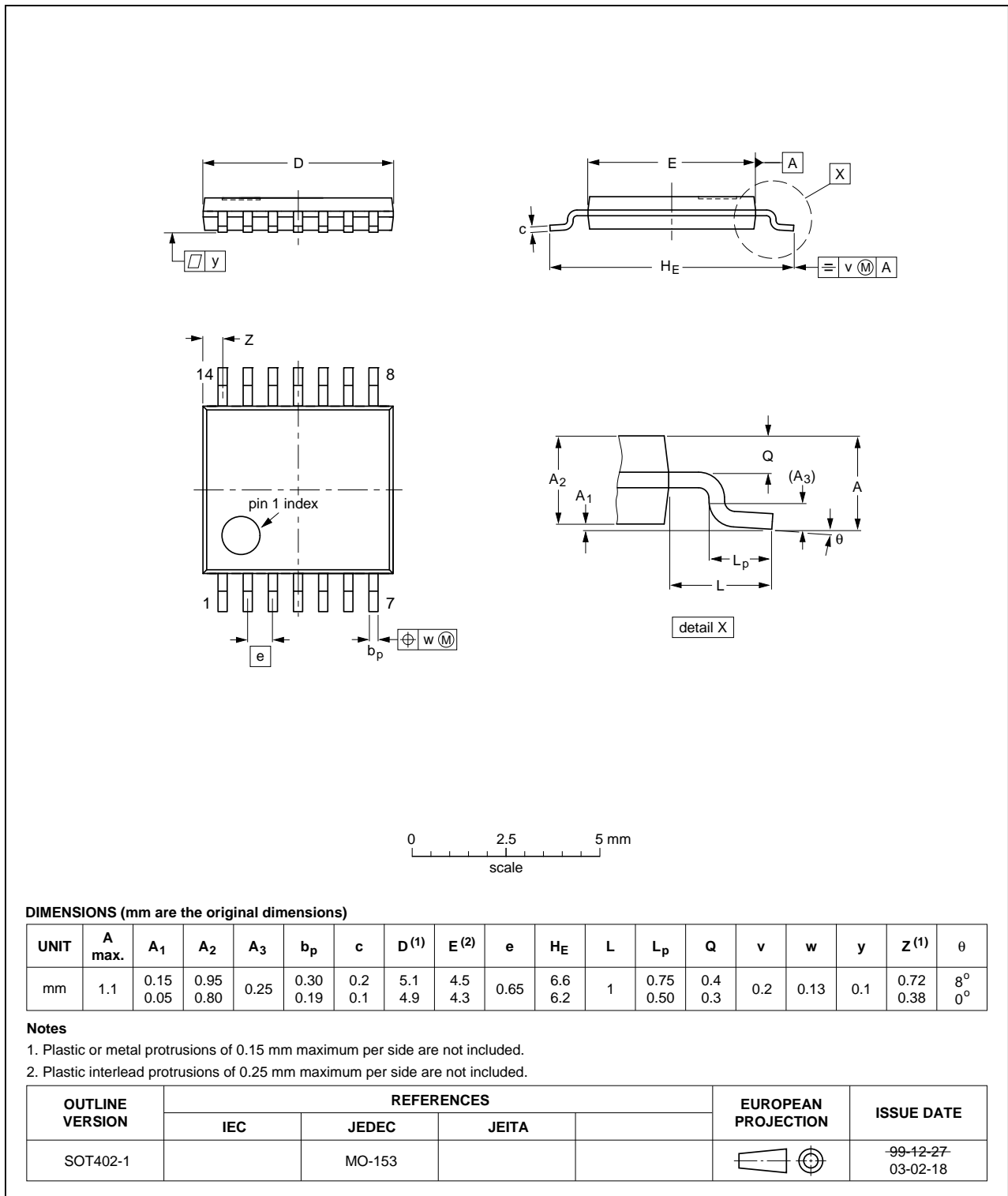


Fig 10. Package outline SOT402-1 (TSSOP14)

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm

SOT762-1

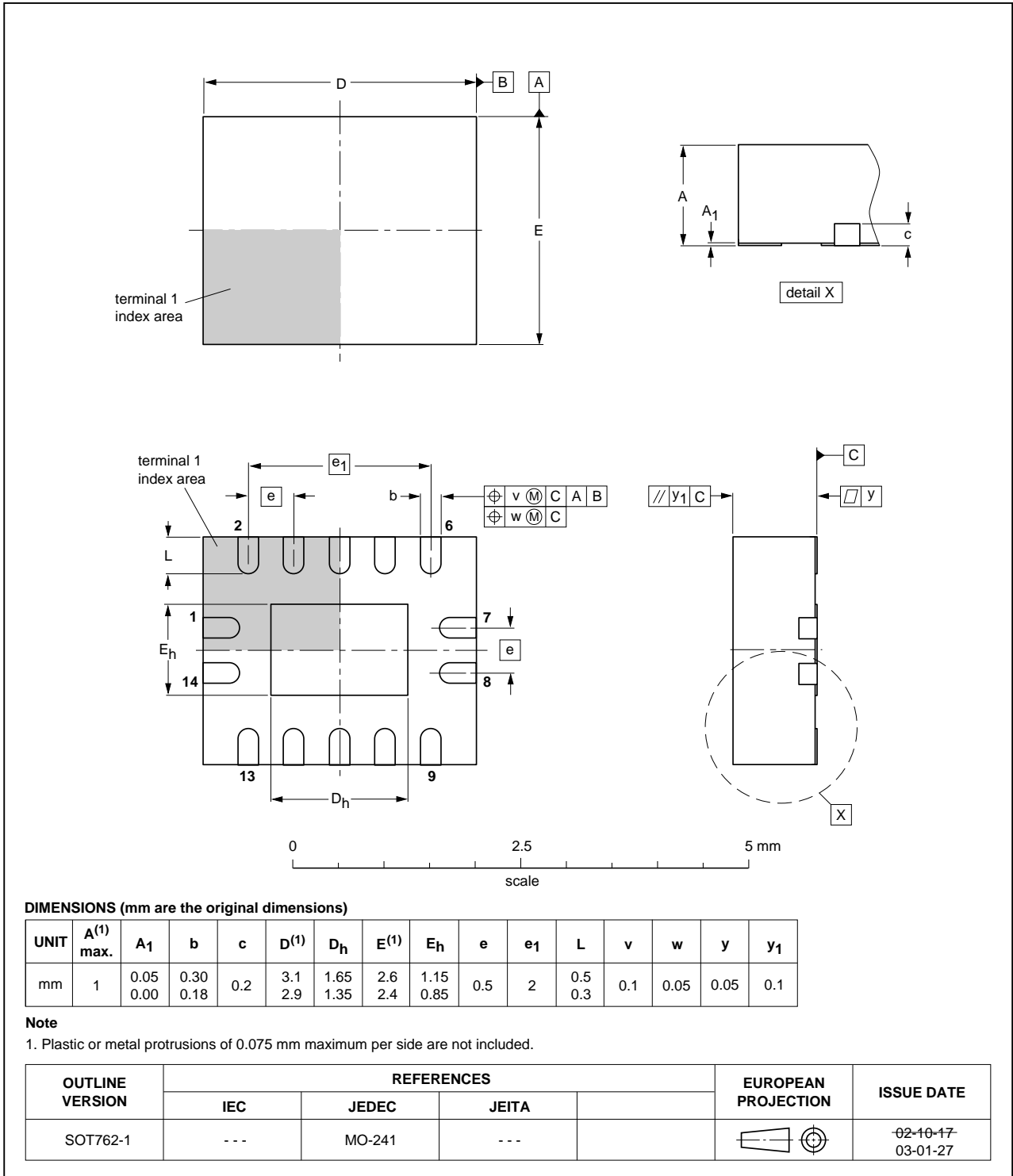


Fig 11. Package outline SOT762-1 (DHVQFN14)

## 13. Abbreviations

Table 9. Abbreviations

| Acronym | Description                 |
|---------|-----------------------------|
| CDM     | Charged Device Model        |
| DUT     | Device Under Test           |
| ESD     | ElectroStatic Discharge     |
| HBM     | Human Body Model            |
| MM      | Machine Model               |
| TTL     | Transistor-Transistor Logic |

## 14. Revision history

Table 10. Revision history

| Document ID  | Release date | Data sheet status  | Change notice | Supersedes |
|--------------|--------------|--------------------|---------------|------------|
| 74LVC332 v.1 | 20130320     | Product data sheet | -             | -          |

## 15. Legal information

### 15.1 Data sheet status

| Document status <sup>[1][2]</sup> | Product status <sup>[3]</sup> | Definition  |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet      | Development                   | This document contains data from the objective specification for product development. |
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[1] Please consult the most recently issued document before initiating or completing a design.

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